

## **Erratum to: The effect of joint size on the creep properties of microscale lead-free solder joints at elevated temperatures**

**Limeng Yin · Song Wei · Zhangliang Xu ·  
Yanfei Geng · Diganta Das · Michael Pecht**

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Unfortunately, the 5th and 6th coauthors were not listed in the author group of the original publication. The revised author group and their affiliations are listed correctly in this erratum.

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The online version of the original article can be found under  
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L. Yin (✉) · S. Wei · Z. Xu · Y. Geng  
School of Metallurgy and Materials Engineering,  
Chongqing University of Science and Technology,  
Chongqing 401331, China  
e-mail: [yinlimeng@cqust.edu.cn](mailto:yinlimeng@cqust.edu.cn)

D. Das · M. Pecht  
Center for Advanced Life Cycle Engineering, University  
of Maryland, College Park, MD 20472, USA